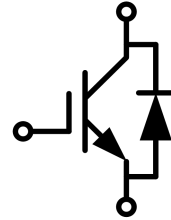


## IGBT Discrete with Anti-Parallel Diode

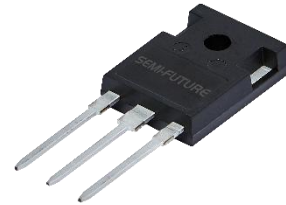
### 电气特性/ Features and Benefits:

- 650V 沟槽栅/场终止工艺  
650V trench gate/field termination process
- 低开关损耗  
Low switching losses
- Vcesat 正温度系数  
Vcesat has a positive temperature coefficient



### 典型应用/ Applications:

- 充电桩  
Charging pile
- 不间断电源  
Uninterruptible power supplies
- 光伏逆变器  
Solar converters



$V_{CES} = 650V$ ,  $I_{C\ nom} = 75A$  /  $I_{CRM} = 300A$

### 关键性能和程序参数 / Key Performance and Package Parameters

Type	$V_{CE}$	$I_C$	$V_{CESat}$ , $T_{vj}=25^{\circ}C$	$T_{vjmax}$	Package
SD75R07A6U	650V	75A	1.56V	175°C	TO-247-3L

## 双极晶体管/IGBT

### 最大额定值 / Maximum Ratings

Parameter	Conditions	Symbol	Value	Unit
集电极-发射极电压 Collector-Emitter voltage	$T_{vj}=25^{\circ}C$	$V_{CES}$	650	V
连续集电极直流电流 Continuous DC collector current	$T_C=100^{\circ}C$ , $T_{vj\ max}=175^{\circ}C$	$I_{C\ nom}$	75	A
集电极重复峰值电流 Repetitive peak collector current	$t_p=1\ ms$	$I_{CRM}$	300	A
栅极-发射极电压 Gate emitter voltage	$t_p \leq 10\ \mu s$ , $D < 0.010$	$V_{GE}$	$\pm 20$ $\pm 30$	V
总功率损耗 Power dissipation	$T_C=25^{\circ}C$ $T_C=100^{\circ}C$	$P_{tot}$	520 260	W

Changes of this product data sheet are reserved.  
Edited by Semi-Future Technologies, Edition 1.0

在开关状态下温度 Temperature under switching conditions		$T_{vj\ op}$	-40...+175	°C
储存温度 Storage temperature		$T_{stg}$	-40...+150	°C
焊接温度 Soldering temperature			260	°C
安装扭矩 Mounting torque		M	0.6	Nm

## 热特性 / Thermal Characteristics

Parameter	Conditions	Symbol	Value	Unit
IGBT 热阻, 结-壳 IGBT thermal resistance, junction - case		$R_{th(j-c)}$	0.29	K/W
二极管热阻, 结-壳 Diode thermal resistance, junction - case		$R_{th(j-c)}$	0.35	K/W

## 特征值 / Characteristic Values

Parameter	Conditions	Symbol	Value			Unit	
			Min.	Typ.	Max.		
集电极-发射极饱和电压 Collector-Emitter saturation voltage	$V_{GE}=15V, I_C=75A$ $V_{GE}=15V, I_C=75A$ $V_{GE}=15V, I_C=75A$	$T_{vj}=25^\circ C$ $T_{vj}=150^\circ C$ $T_{vj}=175^\circ C$	$V_{CEsat}$	1.56 1.86 1.90	2.00	V	
栅极-发射极阈值电压 Gate-Emitter threshold voltage	$I_C=0.75mA, V_{GE}=V_{CE}$	$T_{vj}=25^\circ C$	$V_{GE(th)}$	3.8	4.4	5.0	V
跨导 Transconductance	$V_{CE}=20V, I_C=75A$		$G_{fs}$	58		S	
输入电容 Input capacitance			$C_{ies}$	4472		pF	
输出电容 Output capacitance	$f=100kHz, V_{CE}=25V, V_{GE}=0V$	$T_{vj}=25^\circ C$	$C_{oes}$	171		pF	
反向传输电容 Reverse transfer capacitance			$C_{res}$	20		pF	
门极电荷 Gate charge	$I_C = 75 A, V_{GE} = 15 V,$ $V_{CE} = 520 V$	$T_{vj}=25^\circ C$	$Q_G$	273		nC	
集电极-发射极截止电流 Collector-emitter cut-off current	$V_{CE}=650V, V_{GE}=0V$	$T_{vj}=25^\circ C$	$I_{CES}$		1	mA	
栅极-发射极漏电流 Gate-emitter leakage current	$V_{CE}=0V, V_{GE}=20V$	$T_{vj}=25^\circ C$	$I_{GES}$		200	nA	
开通延迟时间 Turn-on delay time	$I_C=75A, V_{CE}=300V$ $V_{GE}=\pm 15V, R_G=8\Omega$ (电感负载) / (inductive load)	$T_{vj}=25^\circ C$ $T_{vj}=175^\circ C$	$t_{don}$	25 27		ns	
上升时间 Rise time	$I_C=75A, V_{CE}=300V$ $V_{GE}=\pm 15V, R_G=8\Omega$ (电感负载) / (inductive load)	$T_{vj}=25^\circ C$ $T_{vj}=175^\circ C$	$t_r$	130 122		ns	

关断延迟时间 Turn-off delay time	$I_C=75A, V_{CE}=300V$ $V_{GE}=\pm 15V, R_G=8\Omega$ (电感负载) / (inductive load)	$T_{vj}=25^\circ C$ $T_{vj}=175^\circ C$	$t_{doff}$	82 112		ns
下降时间 Fall time	$I_C=75A, V_{CE}=300V$ $V_{GE}=\pm 15V, R_G=8\Omega$ (电感负载) / (inductive load)	$T_{vj}=25^\circ C$ $T_{vj}=175^\circ C$	$t_f$	57 87		ns
开通损耗能量 (每脉冲) Turn-on energy loss per pulse	$I_C=75A, V_{CE}=300V$ $V_{GE}=\pm 15V, R_G=8\Omega$ $di/dt=500A/\mu s(T_{vj}=175^\circ C)$ (电感负载) / (inductive load)	$T_{vj}=25^\circ C$ $T_{vj}=175^\circ C$	$E_{on}$	2.68 3.24		mJ
关断损耗能量 (每脉冲) Turn-off energy loss per pulse	$I_C=75A, V_{CE}=300V$ $V_{GE}=\pm 15V, R_G=8\Omega$ $dv/dt=7800V/\mu s(T_{vj}=175^\circ C)$ (电感负载) / (inductive load)	$T_{vj}=25^\circ C$ $T_{vj}=175^\circ C$	$E_{off}$	1.03 1.51		mJ

## 二极管/Diode

### 最大额定值 / Maximum Ratings

Parameter	Conditions	Symbol	Value	Unit
反向重复峰值电压 Repetitive peak reverse voltage	$T_{vj}=25^\circ C$	$V_{RRM}$	650	V
连续正向直流电流 Continuous DC forward current	$T_C=100^\circ C, T_{vj\max}=175^\circ C$	$I_F$	75	A
正向重复峰值电流 Repetitive peak forward current	$t_p=1ms$	$I_{FRM}$	300	A

### 特征值 / Characteristic Values

Parameter	Conditions	Symbol	Value			Unit
			Min.	Typ.	Max.	
正向电压 Forward voltage	$I_F=75A, V_{GE}=0V$ $I_F=75A, V_{GE}=0V$ $I_F=75A, V_{GE}=0V$	$T_{vj}=25^\circ C$ $T_{vj}=150^\circ C$ $T_{vj}=175^\circ C$	$V_F$	1.55 1.69 1.70	2.0	V
反向恢复峰值电流 Peak reverse recovery current	$I_F=75A,$ $-di_F/dt=500A/\mu s(T_{vj}=175^\circ C)$ $V_R=300V, V_{GE}=-15V$	$T_{vj}=25^\circ C$ $T_{vj}=175^\circ C$	$I_{RM}$	16 26		A
反向恢复电荷 Reverse Recovered charge	$I_F=75A,$ $-di_F/dt=500A/\mu s(T_{vj}=175^\circ C)$ $V_R=300V, V_{GE}=-15V$	$T_{vj}=25^\circ C$ $T_{vj}=175^\circ C$	$Q_{rr}$	1.28 3.18		$\mu C$
反向恢复时间 Reverse Recovery Time	$I_F=75A,$ $-di_F/dt=500A/\mu s(T_{vj}=175^\circ C)$ $V_R=300V, V_{GE}=-15V$	$T_{vj}=25^\circ C$ $T_{vj}=175^\circ C$	$t_{rr}$	156 226		ns
反向恢复损耗 (每脉冲) Reverse recovered energy	$I_F=75A,$ $-di_F/dt=500A/\mu s(T_{vj}=175^\circ C)$ $V_R=300V, V_{GE}=-15V$	$T_{vj}=25^\circ C$ $T_{vj}=175^\circ C$	$E_{rec}$	0.19 0.54		mJ

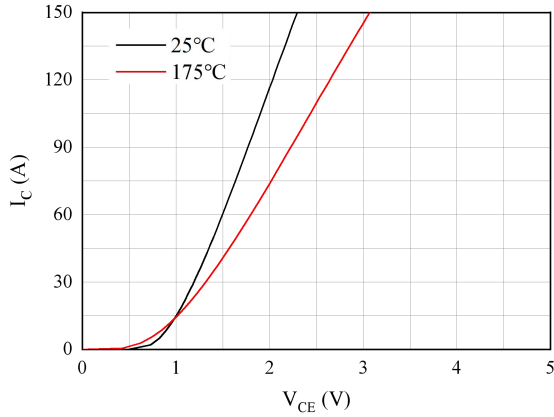


图 1. 典型输出特性 ( $V_{GE}=15V$ )  
Figure 1. Typical output characteristics ( $V_{GE}=15V$ )

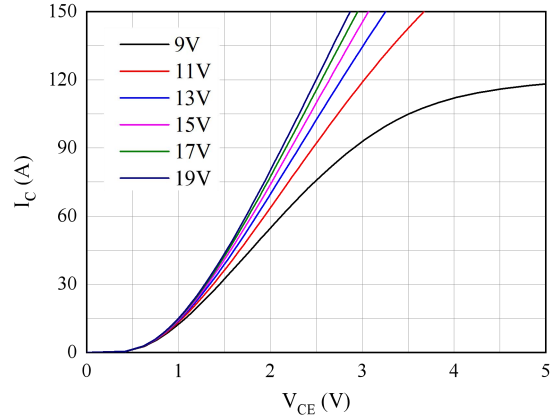


图 2. 典型输出特性 ( $T_{vj}=175^{\circ}C$ )  
Figure 2. Typical output characteristics ( $T_{vj}=175^{\circ}C$ )

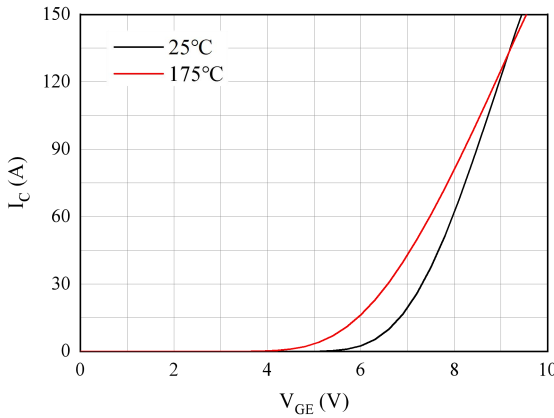


图 3. 典型传输特性 ( $V_{CE}=20V$ )  
Figure 3. Typical transfer characteristic ( $V_{CE}=20V$ )

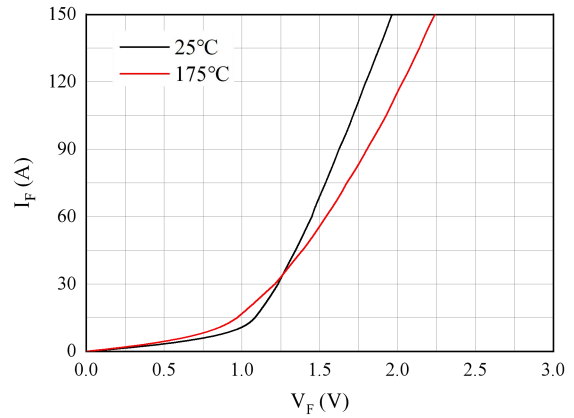


图 4. 正向偏压特性 二极管  
Figure 4. Forward characteristic of Diode

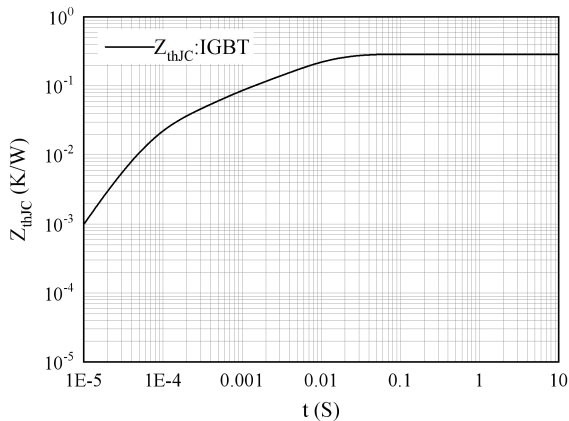


图 5. 瞬态热阻抗 IGBT  
Figure 5. Transient thermal impedance IGBT,  
 $Z_{thJC}=f(t)$

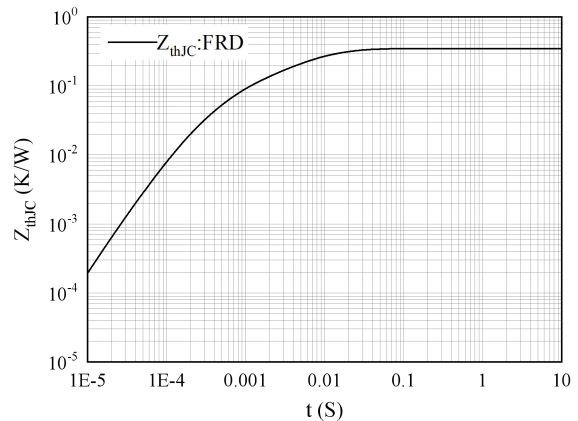


图 6. 瞬态热阻抗 FRD  
Figure 6. Transient thermal impedance FRD,  
 $Z_{thJC}=f(t)$

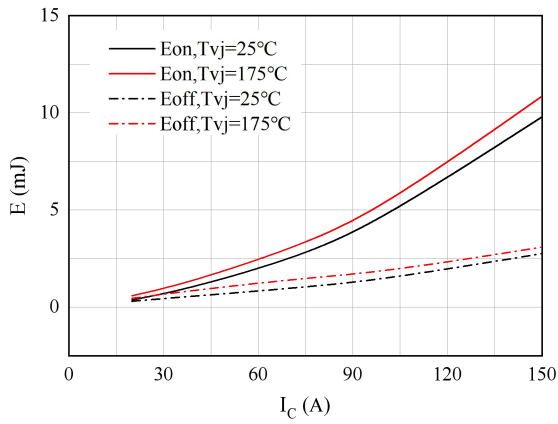


图 7. 开关损耗

Figure 7. Switching losses of IGBT  
 $V_{GE} = \pm 15V, R_{gon} = 8\Omega, R_{goff} = 8\Omega, V_{CE} = 300V$

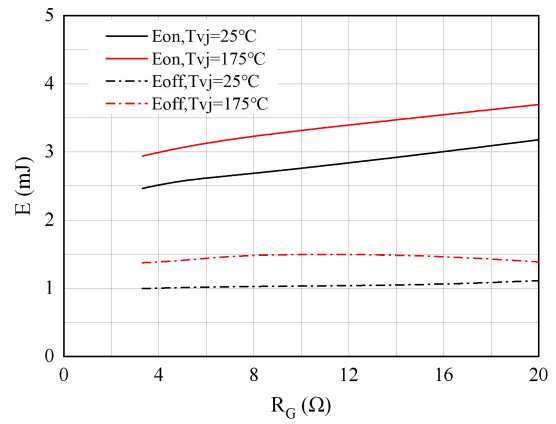


图 8. 开关损耗

Figure 8. Switching losses of IGBT  
 $V_{GE} = \pm 15V, I_c = 75A, V_{CE} = 300V$

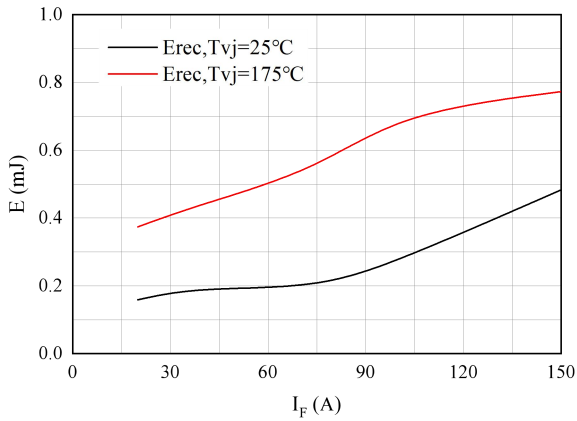


图 9. 开关损耗 二极管

Figure 9. Switching losses of Diode  
 $R_{gon} = 8\Omega, V_{CE} = 300V$

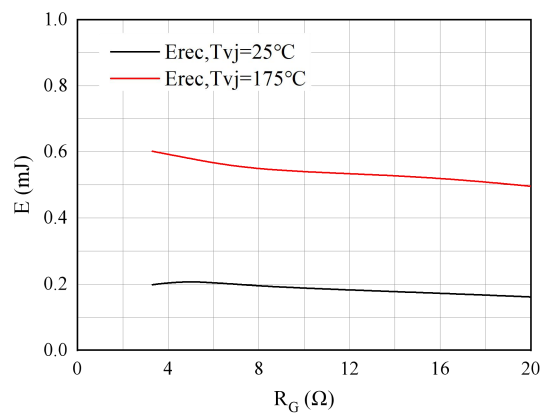


图 10. 开关损耗 二极管

Figure 10. Switching losses of Diode  
 $I_f = 75A, V_{CE} = 300V$

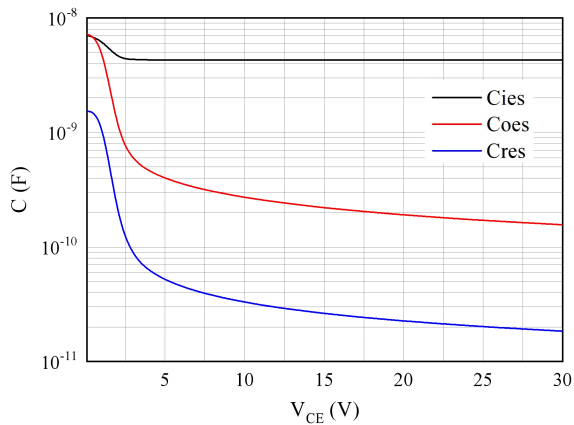
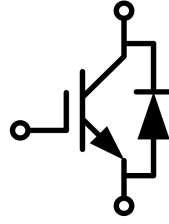


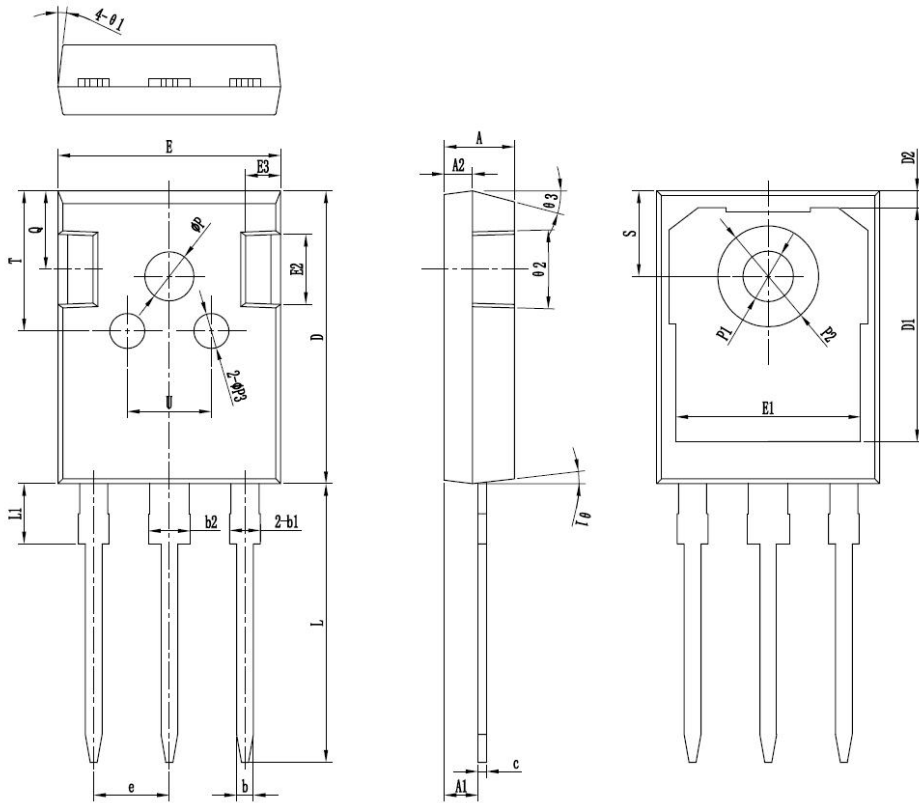
图 11. 电容特性

Figure 11. Capacitance characteristic

接线图 / Circuit diagram



封装尺寸 / Package outlines



符号	单位: mm		
	MIN	NOM	MAX
*H	4.90	5.00	5.10
*H1	2.31	2.41	2.51
A2	1.90	2.00	2.10
*h	1.15	1.20	1.25
*h1	1.95	2.10	2.25
*h2	2.95	3.10	3.25
*c	0.65	0.60	0.65
*d	20.90	21.00	21.10
D1	16.35	16.55	16.75
D2	1.05	1.20	1.35
*e	15.70	15.80	15.90
E1	13.10	13.25	13.40
E2	4.90	5.00	5.10
E3	2.40	2.50	2.60
*e	5.40	5.44	5.48
*L	19.80	19.92	20.10
*L1	-	-	4.30
*PP	3.70	3.80	3.90
*PP1	3.50	3.60	3.70
*PP2	7.00	7.20	7.40
*PP3	2.40	2.50	2.60
Q	5.60	5.80	6.00
*S	6.05	6.15	6.25
T	9.80	10.00	10.20
U	6.00	6.20	6.40
θ1	5°	7°	9°
θ2	1°	3°	5°
θ3	13°	15°	17°

\*为关键管控尺寸